

Product Shortlist - Copper Digital Conductive Inks

Sicrys™ product name	Solvents				Inks								
	Solvent	Viscosity @25°C (cP)	Surface tension (dyn/cm)	Evap. rate @25°C (nBuAc=1)	Solids (Cu ⁰ metal content, %)	% Cu ⁰ in Cu nano- particles	Viscosity @25°C (cP)	Surface tension** (dyn/cm)	Open time (min)(jetting temp.,°C)	Resistivity (μΩcm) (thermal sintering - °C, min, Argon)	Adhesion (tape test 4B-5B)	Printheads tested	Storage
I25EG-1	EG	17.1	48.0	0.01	25%	>90%	26-32	47	5min (35°C)	≤ 5 ^{##} ≤ 32 [#] ≤ 90 (300,30,Ar)	Glass	KM, Dimatix, RICOH	Room temperature under Argon
I50TM-8	TGME	6.2	36.4	<0.01	50%	>95%	26-32	31	20min (40°C)	≤ 5 ^{##} ≤ 120 (300,30,Ar)	Glass, ITO, FR4, Kapton	KM, Dimatix, RICOH	Room temperature under Argon

Notes: ** - ST measured with Pendant Drop method; # - Photonic sintering; ## - Laser sintering.
Solvents: EG - ethylene glycol, TGME - triethylene glycol monomethyl ether.

Rev-1